IAUCN04S6N009T



Automotive MOSFET

OptiMOS™ 6 Power-Transistor







Features

- OptiMOS™ power MOSFET for automotive applications
- N-channel Enhancement mode Normal Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- RoHS compliant
- 100% Avalanche tested
- Top Side Cooling

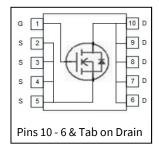
Potential applications

General automotive applications.

Product validation

Qualified for automotive applications. Product validation according to AEC-Q101.





Product Summary

V_{DS}	40	٧
R _{DS(on)}	0.89	mΩ
I _D (chip limited)	330	А

Туре	Package	Marking
IAUCN04S6N009T	PG-LHDSO-10-2	6B4

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Maximum ratings

at Tj=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I _D	V _{GS} =10 V, Chip limitation ^{1,2)}	330	A
		V _{GS} =10V, DC current	120	
		T_a =85 °C, V_{GS} =10 V, R_{thJA} on 2s2p ^{2,4)}	70	
Pulsed drain current ²⁾	I _{D,pulse}	$T_{\rm C}$ =25 °C, $t_{\rm p}$ = 100 μ s	1000	
Avalanche energy, single pulse ²⁾	E AS	/ _D =60 A	380	mJ
Avalanche current, single pulse	I _{AS}	-	95	А
Gate source voltage	V _{GS}	-	±20	V
Power dissipation	P tot	<i>T</i> _C =25 °C	178	W
Operating and storage temperature	$T_{\rm j}$, $T_{\rm stg}$	-	-55 + 175	°C

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Thermal characteristics²⁾

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal resistance, junction - case	R thJC	-	_	0.42	0.84	K/W
Thermal characterization parameter, source pin ⁵⁾	ψ_{source}		_	5.3	-	
Thermal characterization parameter, drain pin ⁶⁾	$\psi_{ extit{drain}}$		-	5.3	-	
Thermal resistance, junction - heatsink ⁴⁾	R _{thJH}		_	6.9	-]
Thermal resistance, junction - ambient ³⁾	R _{thJA}	-	-	49	-	

Electrical characteristics

at T_i=25 °C, unless otherwise specified

Parameter	Symbol	Symbol Conditions		Values		
			min.	typ.	max.	
Static characteristics						
Drain-source breakdown voltage	$V_{\rm (Br)DSS}$	V_{GS} =0 V, I_D =1 mA	40	_	_	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =90 μA	2.2	2.6	3.0	
Zero gate voltage drain current	I _{DSS}	V_{DS} =40 V, V_{GS} =0 V, T_{j} =25 °C	_	_	1	μΑ
		V_{DS} =40 V, V_{GS} =0 V, T_{j} =125 °C ²⁾	-	-	25	
Gate-source leakage current	I _{GSS}	V _{GS} =20 V, V _{DS} =0 V	-	-	100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =7 V, I _D =60 A	-	0.95	1.1	mΩ
		V _{GS} =10 V, I _D =60 A	-	0.79	0.89	
Gate resistance ²⁾	R _G	-	_	0.9	-	Ω



Parameter	Symbol	Symbol Conditions		Values		
			min.	typ.	max.	
Dynamic characteristics ²⁾						
Input capacitance	C iss		-	5650	7345	pF
Output capacitance	C oss	V_{GS} =0 V, V_{DS} =25 V, f =1 MHz	_	1700	2210	
Reverse transfer capacitance	C _{rss}		_	80	120	1
Turn-on delay time	t d(on)	V _{DD} =20 V, V _{GS} =10 V,	_	10	_	ns
Rise time	t _r		-	6	_	
Turn-off delay time	t d(off)	I_{D} =120 A, R_{G} =3.5 Ω	_	25	_	
Fall time	t f		_	12	_	
Gate to source charge Gate to drain charge Gate charge total	Q gs Q gd Q g	V_{DD} =32 V, I_{D} =120 A, V_{GS} =0 to 10 V	- - -	23 17 80	30 26 104	nC
Gate charge total	Q _g	V _{GS} =0 to 10 V	_	80	104	
Gate plateau voltage	$V_{\rm plateau}$		_	4.1	-	V
Reverse Diode						
Diode continous forward current ²⁾	Is	Т _С =25 °С	-	-	120	Α
Diode pulse current ²⁾	I _{S,pulse}	$T_{\rm C}$ =25 °C, $t_{\rm p}$ = 100 μ s	-	-	1000	
Diode forward voltage	V _{SD}	V_{GS} =0 V, I_{F} =60 A, T_{j} =25 °C	_	0.8	1.1	V
Reverse recovery time ²⁾	t rr	V _R =20 V, I _F =50 A,	-	41	-	ns
Reverse recovery charge ²⁾	Q rr	d <i>i</i> _F /d <i>t</i> =100 A/μs	_	38	_	nC

¹⁾ Practically the current is limited by the overall system design including the customer-specific PCB.

²⁾ The parameter is not subject to production testing – specified by design.

³⁾ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.

⁴⁾ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7) without thermal vias, heatsink of 71x110x2 mm is attached through 3 W/(m*K) 400μm to top side pad. Heatsink fixed to 85°C ambient temperature.

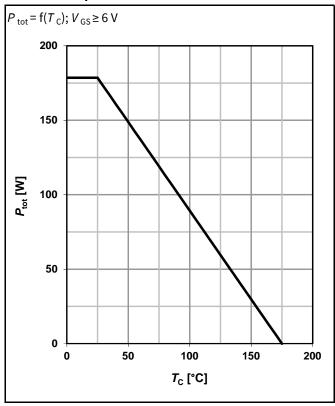
⁵⁾ Thermal characterization parameter, calculated as $\psi_{\text{source}} = (T_{\text{source}} - T_{\text{ambient}})/P_{\text{dis}}$ in condition of 4). Used to determine PCB temperature at source pins for given power.

⁶⁾ Thermal characterization parameter, calculated as $\psi_{drain} = (T_{drain} - T_{ambient})/P_{dis}$ in condition of 4). Used to determine PCB temperature at drain pins for given power.

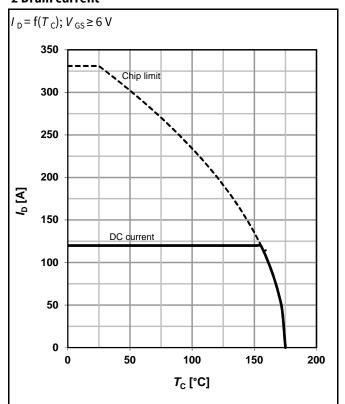


Electrical characteristics diagrams

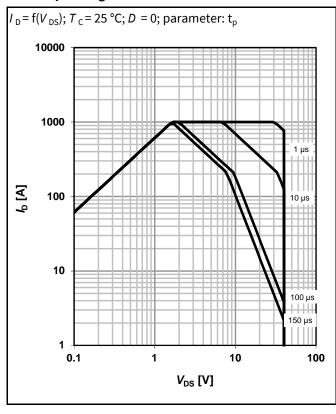
1 Power dissipation



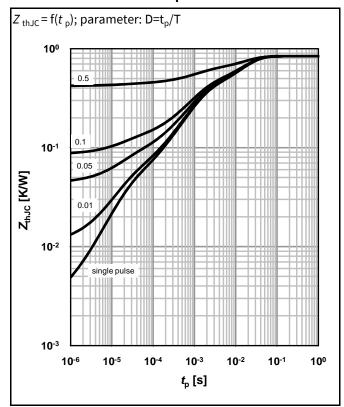
2 Drain current



3 Safe operating area

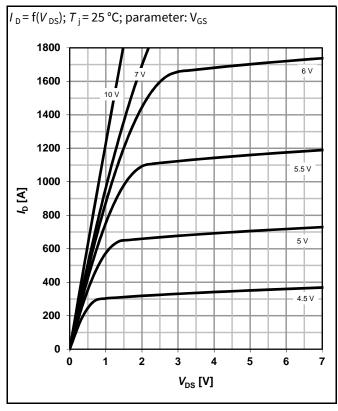


4 Max. transient thermal impedance

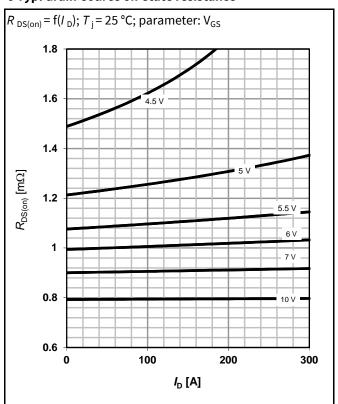




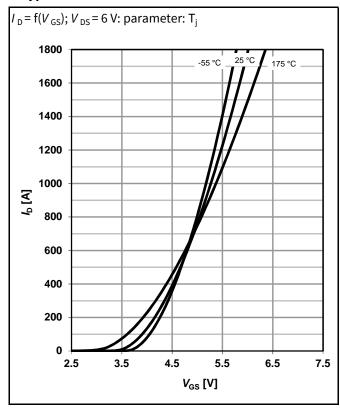
5 Typ. output characteristics



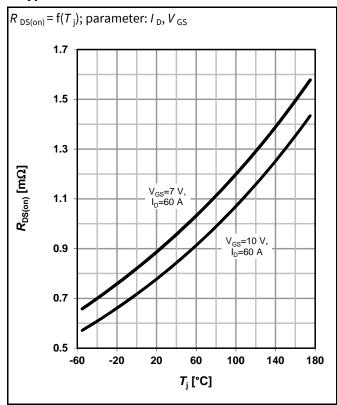
6 Typ. drain-source on-state resistance



7 Typ. transfer characteristics

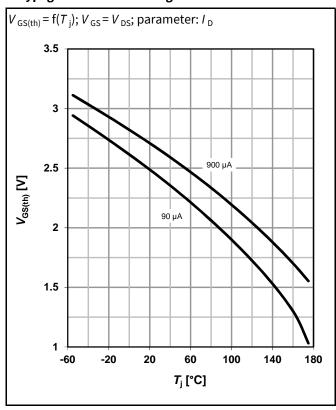


8 Typ. drain-source on-state resistance

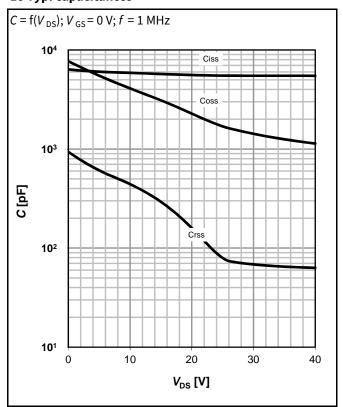


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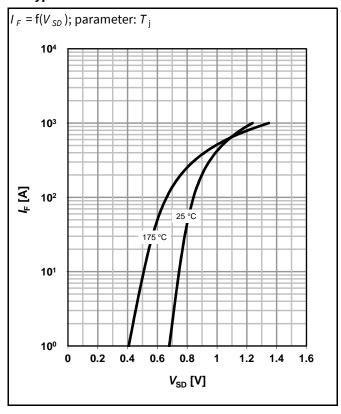
9 Typ. gate threshold voltage



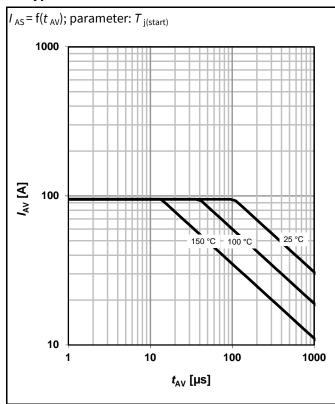
10 Typ. capacitances



11 Typical forward diode characteristics

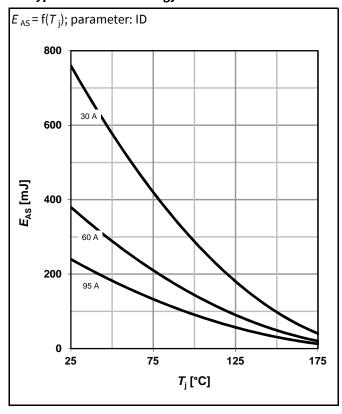


12 Typ. avalanche characteristics

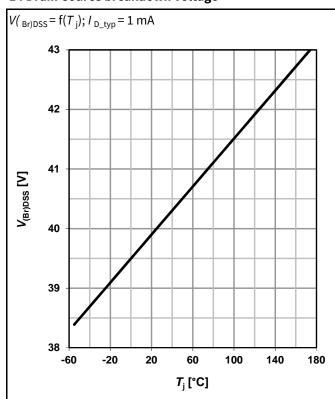


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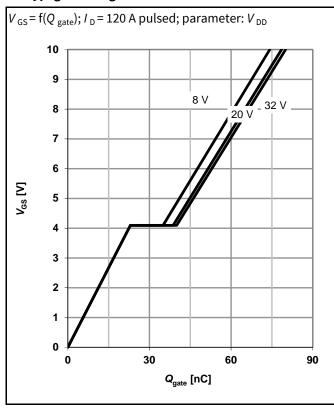
13 Typical avalanche energy



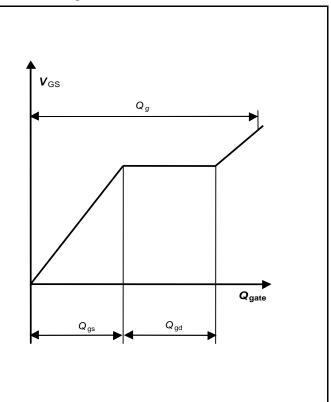
14 Drain-source breakdown voltage



15 Typ. gate charge



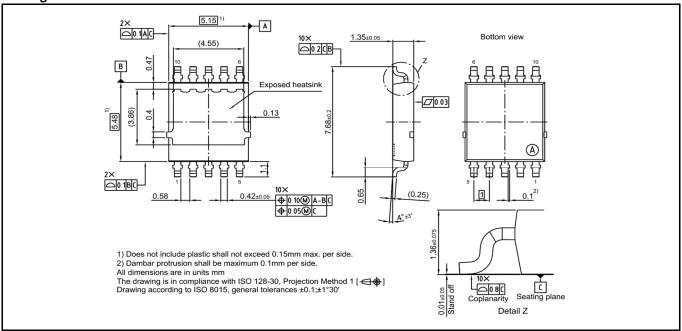
16 Gate charge waveforms



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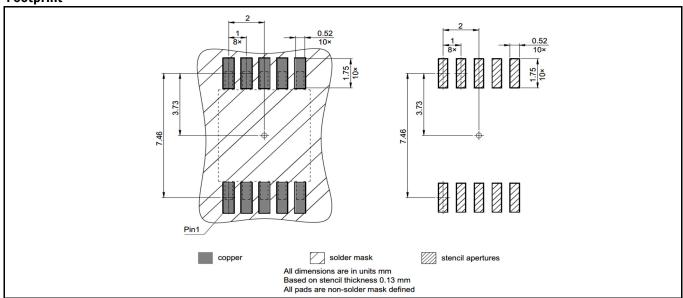


Package Outline

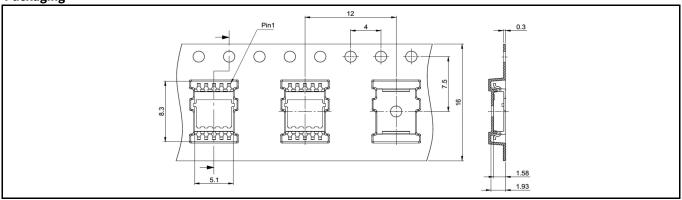


https://www.infineon.com/cms/en/product/packages/PG-LHDSO/PG-LHDSO-10-2





Packaging



all dimensions in mm

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Revision History

Revision	Date	Changes
Revision 1.1	21.08.2023	Final Data Sheet

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Edition 2023-08-21

Published by

Infineon Technologies AG

81726 Munich, Germany

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Document reference IAUCN04S6N009T-Data-Sheet-11-Infineon

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